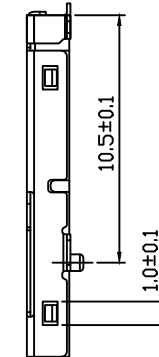
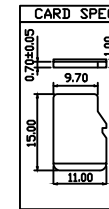
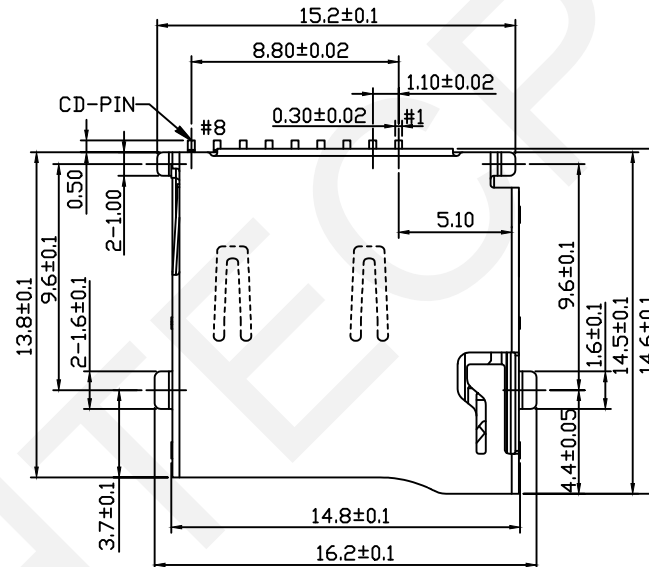
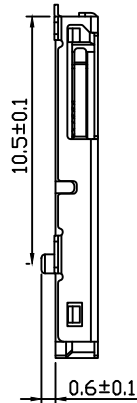
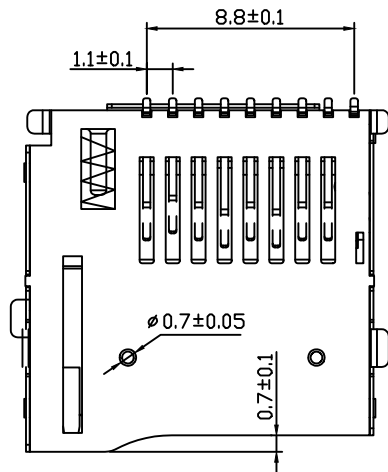


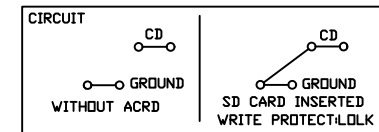
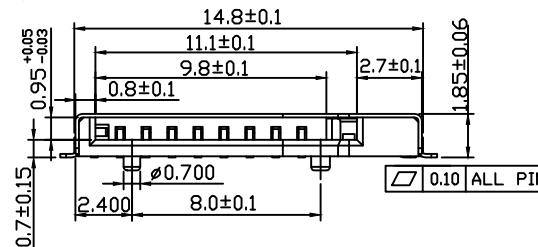
Material:

Insulator: High Temperature Thermoplastic, LCP, UL94V-0.
 Contact: Copper Alloy T=0.15, Plated 50u" Ni Overall. Plated Au Selective Contact
 Area Plated 30u"-70u" Sn Over Ni On Solder Area.
 Shell: T=0.15, Plated 30u" Ni Overall Min. Plated 0.5u" Au Selective Contact Area



Electrical:

Current Rating: 0.5mA AC/DC max.
 Voltage Rating: 125V AV/DC
 Ambient Temperature Range: -25°C~+85°C
 Storage Temperature Range: -25°C~+85°C
 Ambient Humidity Range: 95% R.H.Max.
 Contact Resistance: 100mΩ Max
 Insulation Resistance: 1000MΩ Min./500VDC
 Mating Cycles: 5000 Insertions.
 Peak Temperature: 260°C±0.5°C

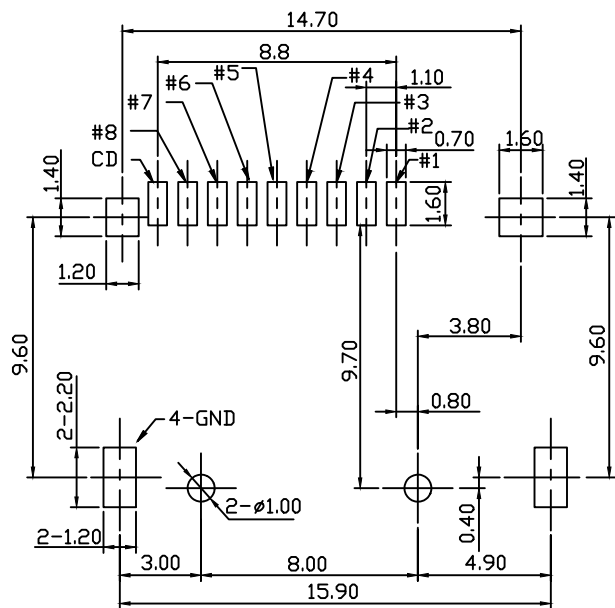


NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4	SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5
CHK'D BY FENG		APPR BY ZHAN	

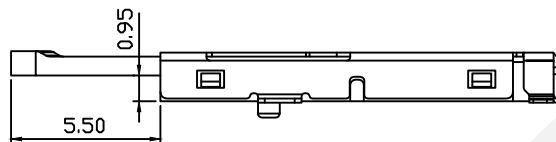
Micro SD Card CONN: PUSH/PUSH,
 H1.85mm, SMD With CD Pin, GOLD
 THIRD ANGLE PROJECTION
 RHTAYF-003C-H1.9-R

RoHS Compliance

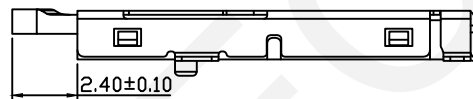


PIN NO.	PIN ASSIGNMENT
1#	DAT2
2#	CD/DAT3
3#	CMD
4#	VDD
5#	CLK
6#	VSS
7#	DAT0
8#	DAT1
9#	CD

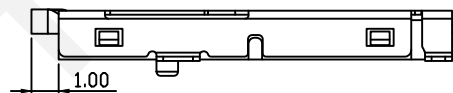
T-Flash Card Insert Drawing:



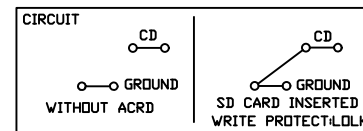
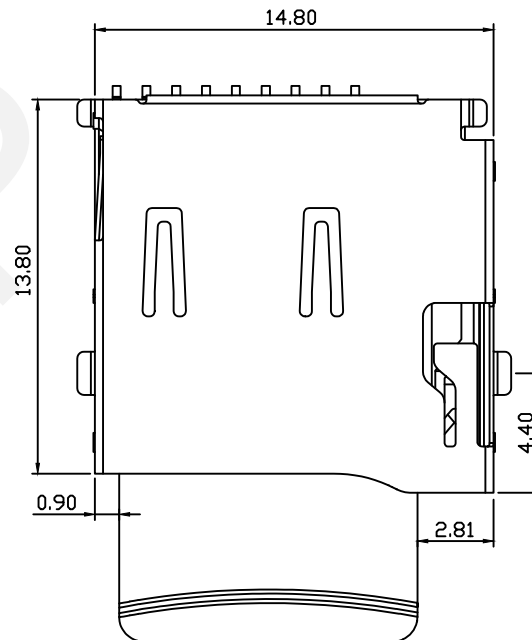
Micro SD Card-Un Lock



Micro SD Card-Lock



Micro SD Card-Push



RHTECP NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm SHEET SIZE: A4 SCALE:---
 DRWN BY PAN
 0~3 3~18 18~50 50~120
 CHK'D BY FENG
 ±0.12 ±0.15 ±0.3 ±0.5
 APPR BY ZHAN

Micro SD Card CONN:PUSH/PUSH,
 H1.85mm,SMD With CD Pin,GOLD
 THIRD ANGLE PROJECTION

 RHTAYF-003C-H1.9-R